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P.R. Amth. B

RD-26,616

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of
R.A. Fillion and W.E. Burdick

Applicant's Docket No. RD-26,616

For

CHIP BURN-IN AND TEST STRUCTURE AND METHOD

PRELIMINARY AMENDMENT

Honorable Commissioner of Patents and Trademarks,
Washington, DC 20231

S I R:

Prior to examination, please amend this application as follows.

In the title, please delete "AND METHOD."

In the claims, please amend claim 12 and add claims 14-17 as follows.

¹
~~12.~~ A burn-in fixture comprising:
burn-in frame having at least one window and including resistors having resistor pads;
at least one integrated circuit chip having chip pads and situated in the at least one
window;
a flexible layer attached to the burn-in frame and the at least one integrated circuit chip,
the flexible layer having via openings extending to the chip pads and the resistor pads; and
a pattern of electrical conductors extending over the flexible layer and extending into the
vias [; and
means for burning in the at least one integrated circuit chip].

³
~~14~~ (new). The fixture of claim ~~12~~¹ wherein the burn-in frame comprises a ceramic or
an insulated metal.

⁴
~~15~~ (new). The fixture of claim ~~14~~³ wherein the flexible layer comprises a polymer.

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